Packaging and Thermal Characteristics

Products Guide
Product Data Sheets
Package Drawings
Packaging and Thermal
Characteristics

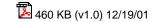
Application Notes
White Papers
Software/Hardware
Manuals

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- Package Drawings
- Thermal Packaging Management Application Note XAPP415



Package Information

This section contains the following information:

- Inches and Millimeters
- Dimensions for Xilinx Quad Flat Packs
- Suggested Board Layout of Soldered Pads for BGA Packages
- Recommended PCB Design Rules
- Cavity Up or Cavity Down
- Clockwise or Counterclockwise
- Summary of Thermal Resistance for Packages
- Package Electrical Characterization
 This patient of the following information
 - This section contains the following information:
 - Theoretical Background
 - Analytical Formulas for Lead Inductance
 - General Measurement Procedure
 - Data Acquisition and Package Electrical Database
- Component Mass (Weight) by Package Type
- Thermally Enhanced Packaging This section contains the following information:
 - The Package Offering
 - Overview
 - Where and When Offered
 - Mass Comparison
 - · Thermal Data for the HQ
- Moisture Sensitivity of PSMCs

This section contains the following information:

- Moisture Induced Cracking During Solder Reflow
- Package Moisture Sensitivity Levels per J-STD-020
- Factory Floor Life
- Dry Bake Recommendation and Dry Bag Policy
- Handling Parts in Sealed Bags

Tape and Reel

This section contains the following information:

- Benefits
- Cover Tape
- Reel
- Bar Code Label
- Shipping Box
- Tape and Reel Packaging

Reflow Soldering Process Guidelines This section contains the following information:

- Solder Reflow ProcessSoldering Problems SummaryTypical Conditions for IR Reflow
- Typical Conditions for Vapor Phase Reflow Soldering

Sockets NEW!

This section contains the following information:

Socket Manufacturers